



# **iJRASET**

International Journal For Research in  
Applied Science and Engineering Technology



---

# **INTERNATIONAL JOURNAL FOR RESEARCH**

IN APPLIED SCIENCE & ENGINEERING TECHNOLOGY

---

**Volume: 10    Issue: VI    Month of publication: June 2022**

**DOI: <https://doi.org/10.22214/ijraset.2022.44867>**

**[www.ijraset.com](http://www.ijraset.com)**

**Call:  08813907089**

**E-mail ID: [ijraset@gmail.com](mailto:ijraset@gmail.com)**

# Analysis of Electronic Cooling with Natural Convection and Radiation

P. Siva Naga Sree<sup>1</sup>, K. N Ravi Teja<sup>2</sup>, B. Guru Chand<sup>3</sup>, P. Harsha Vardhan Reddy<sup>4</sup>, A. Rokesh Kumar<sup>5</sup>, U. Mohan Sandeep<sup>6</sup>

<sup>1, 2, 3, 4, 5, 6</sup>Department of Mechanical Engineering, DMSSVH College Of Engineering, Machilipatnam, Andhra Pradesh, India.

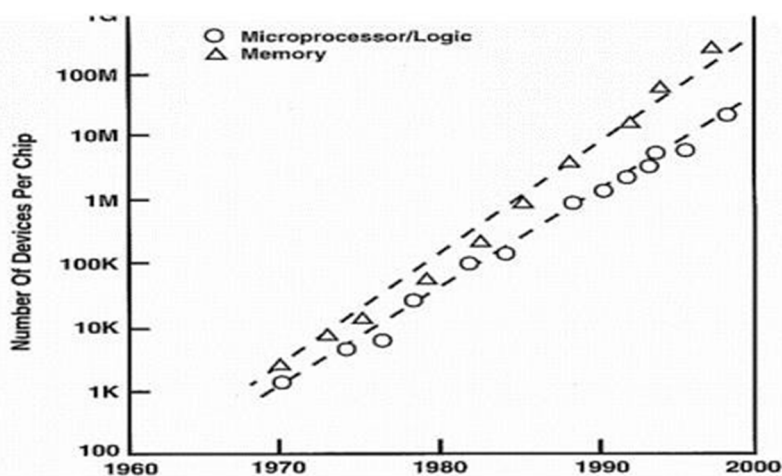
**Abstract:** The size of the electronic instruments as day by day decreases drastically and simultaneously the number of functions per chip increases hugely. So, it's a great challenge to remove the heat generated by the chip efficiently. Many kinds of research works are going on in this direction for the past few decades. In this study the cooling effects of the chip are analyzed using CFD simulations. The single chip module is modelled using space claim. The analysis is carried out in static module by solving the governing equations for a flow through a channel via obstruction. The laminar flow is assumed for the temperature variation analysis in the chip. The three metals are copper, aluminium and silver are analyzed for temperature variation in chip. Form this analysis it was found that silver is the best metal to transfer the heat from the chip.

**Keywords:** Electronics cooling, CFD, chips, cooling effect.

## I. INTRODUCTION

Since the development of the first electronic digital computers in the 1940s, the effective removal of heat has played a key role in ensuring the reliable operation of successive generations of computers. The Electrical Numerical Integrator and Computer (ENIAC), dedicated in 1946, has been described as a "30-ton, boxcar-sized machine requiring an array of industrial cooling fans to remove the 140 KW dissipated from its 18,000 vacuum tubes". In the year 1947 the first transistor was successfully demonstrated the development of generations of computers yet to come. As a replacement for vacuum tubes, the miniature transistor generated less heat, was much more reliable, and promised lower production costs.

During the 1960s small scale and then medium scale integration (SSI) and (MSI) led from one device per chip to hundreds of devices per chip. The trend continued through the 1970s with the development of large-scale integration (LSI) technologies offering hundreds to thousands of devices per chip. In 1980s with the development of very large-scale integration technologies offering thousands to tens thousands of devices per chip. It leads to be increase in temperature when the chip in working.



The usage of electronic components liberates high heat because it consists of electronic chips. During working condition electronic chips liberate high heat. if we didn't remove the heat from the chips thus causes the material damage or properties of material change or sometimes leads to blast.

## II. MODELING AND ANALYSIS

### A. Modeling A Chip

In this work modelling of chip is done using space claim software considering chip as a heat source and tip of the chip as heat sink. The modelling of the chip is shown in Fig 1 to Fig 2.

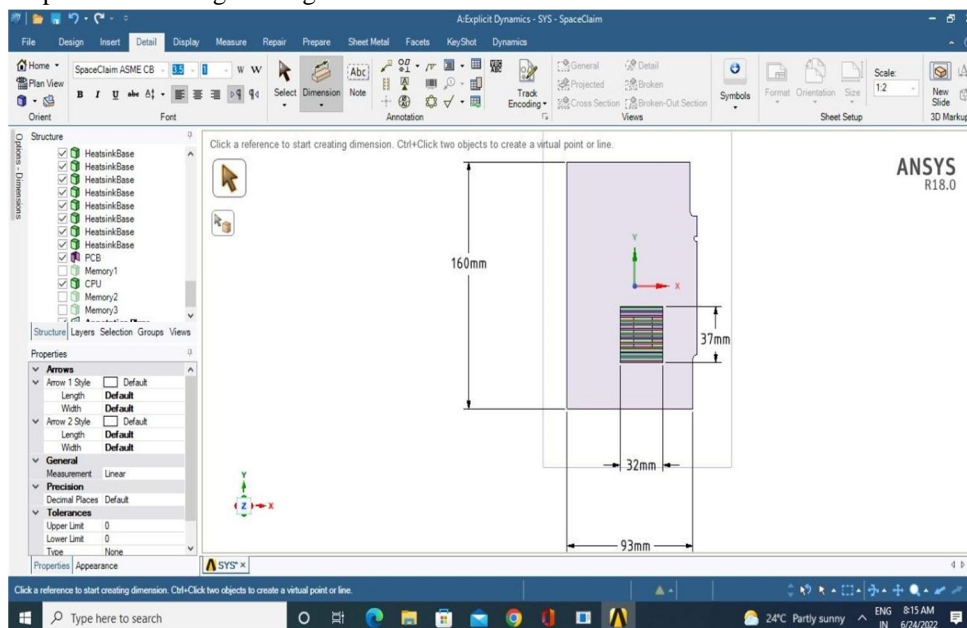


Fig 1 Electronics chip top view

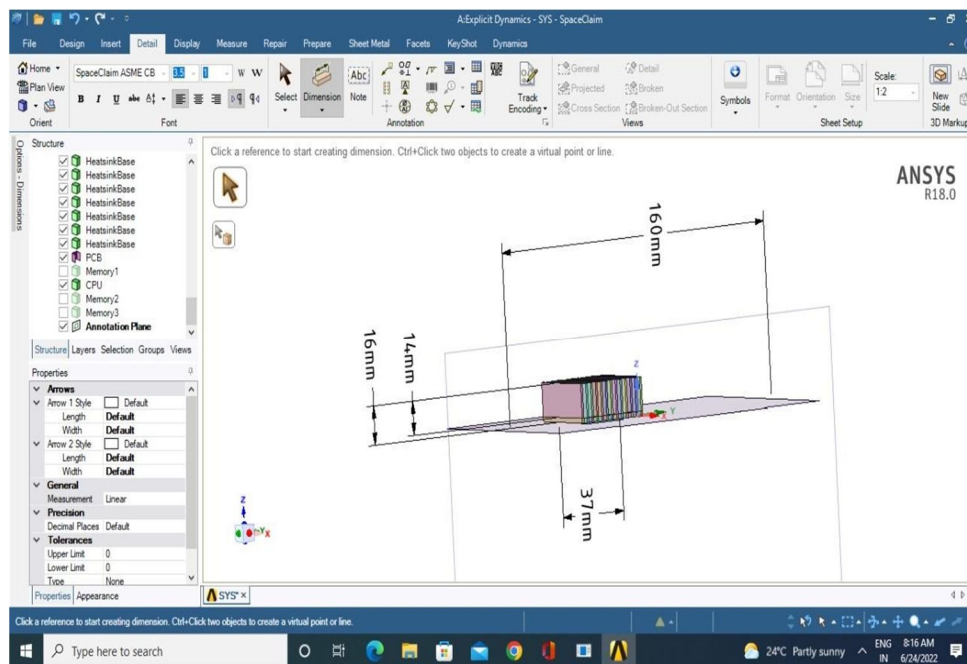


Fig 2 Electronics chip side view

### B. Materials

The materials used in this project for chip are copper, aluminum and silver. The properties of copper are density 8978 kg/m<sup>3</sup>, specific heat is about 381 j/kg-k, and thermal conductivity is 387.6 w/m-k. Aluminium (Al) density is 2,710kg/m<sup>3</sup>, specific heat is about 900 j/kg-k, thermal conductivity is 247w/m-k. Silver (Ag) density is 10800kg/m<sup>3</sup>, specific heat is about 0.237 j/kg-k, thermal conductivity is about 419w/m-k.



**C. Apply Boundary Conditions**

The project implies that it is a NATURAL CONVECTION that means we didn't use any external forces to cool the chip. The one boundary condition is given for the chip that is temperature at the inlet, the emissivity given to the wall is 0.9.

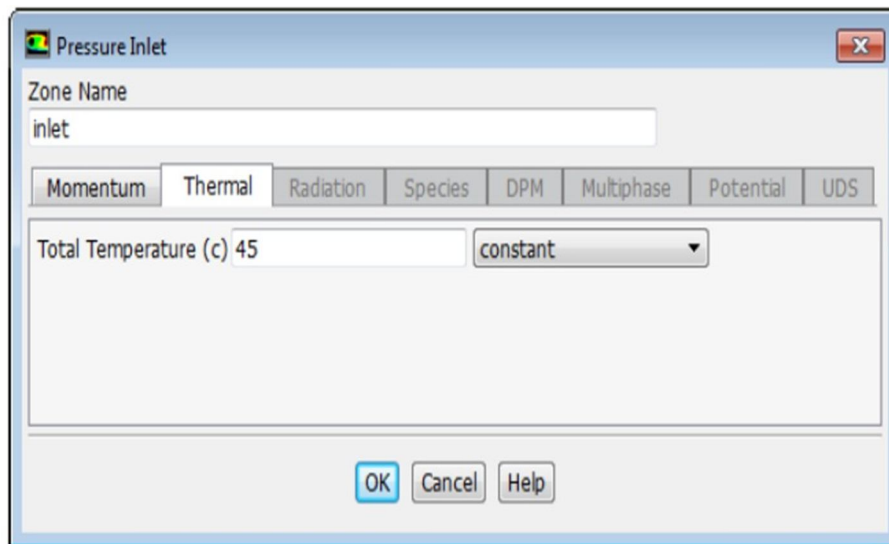


Fig 3 Inlet temperature

**III. RESULTS AND DISCUSSION**

By using the natural convection with radiation, the thermal analysis of chip with three different materials are shown in Fig .... The three materials sink temperatures are shown in table ... For aluminum the sink temperature is about 360 K for copper it 365 K. It is observed from the results that chip made of silver is having highest sink temperature of 370 K indicating that maximum heat transfer occurs from the chip.

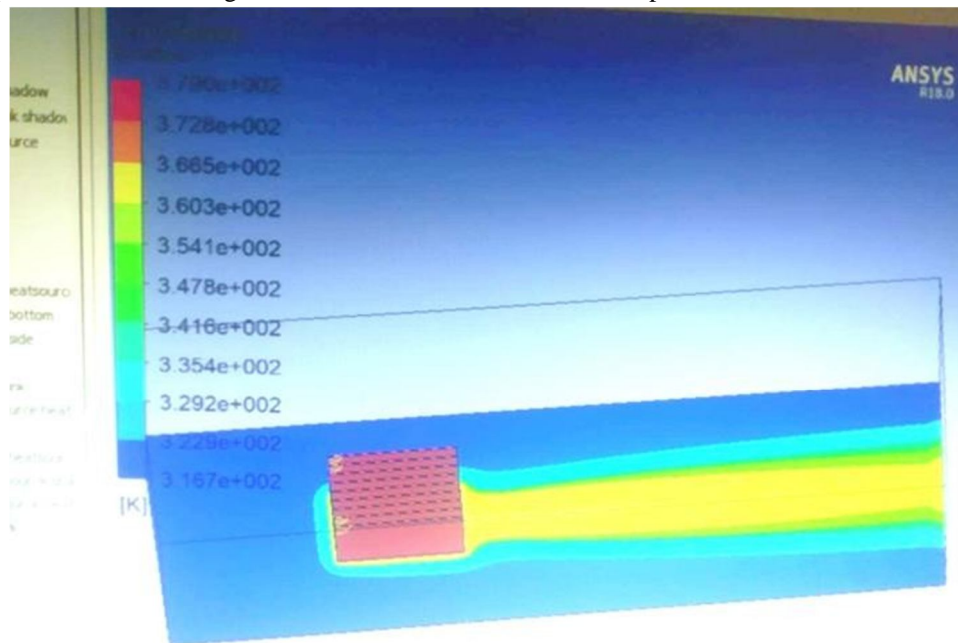


Fig 4 CFD analysis for aluminium

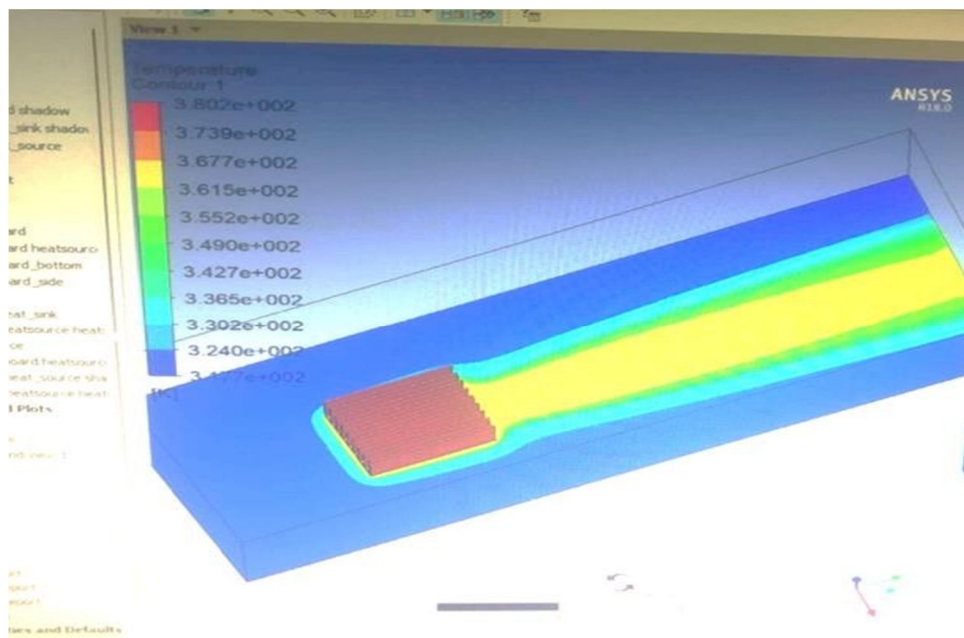


Fig 5 CFD analysis for copper

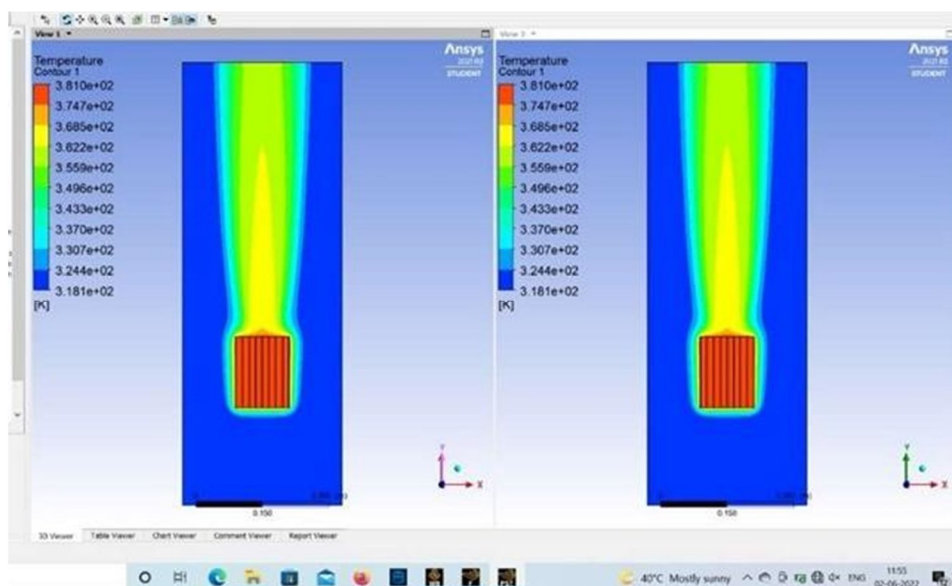


Fig 6 CFD analysis for silver SINK SINK TEMPERATURE FOR COPPER, SILVER AND ALUMINIUM.

S.NO	MATERIALS	Sink TEMPERATURE
01	ALUMINIUM	360 k
02	COPPER	364.5 k
03	SILVER	369.5 k

#### IV. CONCLUSIONS

The electronic chip cooling is analyzed using computational fluid dynamics. The temperature variation in the sink of chip utilizing copper, aluminum, and silver is obtained. It is concluded that silver is the best material to remove the heat generated in the electronics compared to copper and aluminum.



## REFERENCES

- [1] Chang YW, Cheng CH, Wang JC and Chen SL. Heat pipe for cooling of electronic equipment. *Energy Conversion and Management*. 2008; 49(11):3398-3404.
- [2] Lasance C and Simons R. Advances in high performance cooling for electronics. *Electronics Cooling*. 2005; 11(4):22-39
- [3] Murshed SMS, Leong KC, Yang C. Thermophysical and electrokinetic properties of nanofluids: a critical review. *Applied Thermal Engineering*. 2008; 28:2109-2125.
- [4] Murshed SMS, Nieto de Castro CA, Lourenço MJV, Lopes MLM and Santos FJV. A review of boiling and convective heat transfer with nanofluids. *Renewable and Sustainable Energy Reviews*. 2011; 15:2342-2354.
- [5] Murshed SMS and Nieto de Castro CA. Boiling heat transfer and droplet spreading of nanofluids. *Recent Patents on Nanotechnology*. 2013; 7:216-223.
- [6] Murshed SMS and Nieto de Castro CA. *Nanofluids: Synthesis, Properties and Applications*. New York: Nova Science Publishers. 2014.
- [7] Murshed SMS and Nieto de Castro CA. Superior thermal features of carbon nanotubes based nanofluids: a review. *Renewable and Sustainable Energy Reviews*. 2014; 37:155-167.
- [8] Wong KV and De Leon O. Applications of nanofluids: current and future. *Advances in Mechanical Engineering*. 2010; 2010: (ID 519659) 11.
- [9] Murshed SMS and Nieto de Castro CA. Nanofluids as advanced coolants. In: *Green Solvents I: Properties and Applications in Chemistry*, Ed., Mohammad A and Inamud- din, 397-415. London: Springer. 2012. Nieto de Castro CA, Lourenço MJV, Ribeiro APC, Langa E, Vieira SIC, Goodrich P,







10.22214/IJRASET



45.98



IMPACT FACTOR:  
7.129



IMPACT FACTOR:  
7.429



# INTERNATIONAL JOURNAL FOR RESEARCH

IN APPLIED SCIENCE & ENGINEERING TECHNOLOGY

Call : 08813907089  (24\*7 Support on Whatsapp)